



Final Product/Process Change Notification

Document #:FPCN23660ZA

Issue Date: 28 Jul 2023

Title of Change:	Qualification of onsemi Aizu Japan as wafer Fab for ONC25BCD Technology for select products in NCV20072 family.	
Proposed Changed Material First Ship Date:	04 Feb 2024 or earlier if approved by customer	
Current Material Last Order Date:	N/A <i>Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.</i>	
Current Material Last Delivery Date:	N/A <i>The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory</i>	
Product Category:	Active components – Integrated circuits	
Contact information:	Contact your local onsemi Sales Office or Adrian.Croitoru@onsemi.com	
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Sample Availability Date:	30 Jun 2023	
PPAP Availability Date:	30 Aug 2023	
Additional Reliability Data:	Contact your local onsemi Sales Office or Vladislav.Hrachovec@onsemi.com	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com .	
Change Category		
Category	Type of Change	
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor	
Description and Purpose:		
onsemi would like to inform its customers of qualification of a wafer fabrication facility for ONBCD25 technology at onsemi Aizu, Japan and a Back Grinding site transfer to onsemi ISMF, for the devices listed in this FPCN. All products listed here will be sourced only from onsemi Aizu. There is no change to the orderable part number. There is no product marking change as a result of this notification.		
NCV20072 Family – SOIC-8, TSSOP-8 and Micro-8 packages	From	To
Wafer Fab	onsemi, Gresham, Oregon (US)	onsemi, Aizu (Japan)
Back Grinding	onsemi, Gresham, Oregon (US)	onsemi, ISMF (Seremban)

Reason / Motivation for Change:	Capacity improvement			
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by onsemi in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.			
Sites Affected:				
onsemi Sites		External Foundry/Subcon Sites		
onsemi Aizu, Japan		None		
onsemi, ISMF Malaysia				
Marking of Parts/ Traceability of Change:	Custom source information will be updated on product label. Product traceability will be identified by encoded date code.			
Reliability Data Summary:				
QV DEVICE NAME: NCV20072DR2G RMS: O86311 PACKAGE: SOIC-8				
Test	Specification	Condition	Interval	Results
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs	0/231
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs	0/231
Early Life Failure Rate	JESD22-A108	Ta=125°C, 100 % max rated Vcc	48 hrs	0/2400
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260°C, Pre TC, uHAST, HAST for surface mount pkgs only		0/all
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
NOTE: AEC-1pager is attached. <i>To view attachments:</i> 1. Download pdf copy of the PCN to your computer 2. Open the downloaded pdf copy of the PCN 3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field 4. Then click on the attached file.				
Electrical Characteristics Summary:				
Electrical characteristics are not impacted.				



Final Product/Process Change Notification

Document #:FPCN23660ZA

Issue Date: 28 Jul 2023

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Current Part Number	New Part Number	Qualification Vehicle
NCV272DMR2G	NA	NCV20072DR2G
NCV272DR2G	NA	NCV20072DR2G
NCV20072DTBR2G	NA	NCV20072DR2G
NCV20072DMR2G	NA	NCV20072DR2G
NCV20072DR2G	NA	NCV20072DR2G

Appendix A: Changed Products

PCN#: FPCN23660ZA
Issue Date: Jul 28, 2023

DIKG: DIGI-KEY

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NCV272DMR2G		NCV20072DR2G	NA	
NCV20072DTBR2G		NCV20072DR2G	NA	
NCV20072DMR2G		NCV20072DR2G	NA	
NCV20072DR2G		NCV20072DR2G	NA	
NCV272DR2G		NCV20072DR2G	NA	